

S/N 10/747,927

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Koning et al.

Examiner: Cuong Quang Nguyen

Serial No.: 10/747,927

Group Art Unit: 2811

Filed: December 30, 2003

Docket No.: 884.863US1

Title: NANOTUBE MODIFIED SOLDER THERMAL INTERMEDIATE STRUCTURE,
SYSTEMS, AND METHODS

Assignee: Intel Corporation

Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on June 15, 2006. Please amend the above-identified patent application as follows.